

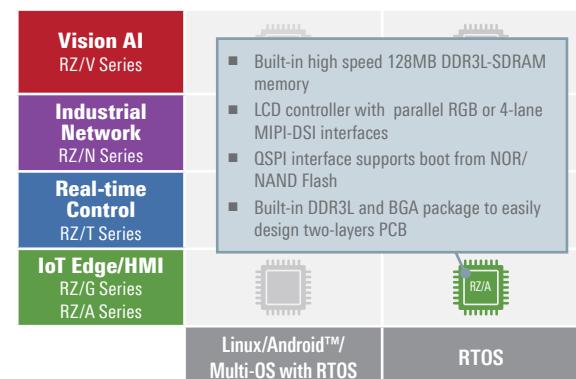
## Optimize Speed and Graphics Performance for High-Definition HMIs

# RENESAS RZ/A3M GROUP

### 64bit Arm® Cortex®-A55 MPU (1GHz) with built-in DDR3L SDRAM

The RZ/A3M MPUs based on the Arm® Cortex®-A55 (CA55) core with NEON™ extension and built-in large capacity 128MB DDR3L memory are equipped with a feature set optimized to address diverse human-machine interface (HMI) for consumer, smart home and building automation, healthcare, industrial applications, and office automation market segments.

The RZ/A3M MPUs also integrate features such as high-resolution Graphics LCD controller with parallel RGB and 4-lane MIPI-DSI interfaces to display panels, 2D graphics drawing engine, support QSPI NOR/NAND Flash for large-size programs, and 244 pin LFBGA package which is ideal for 2-layers board design.



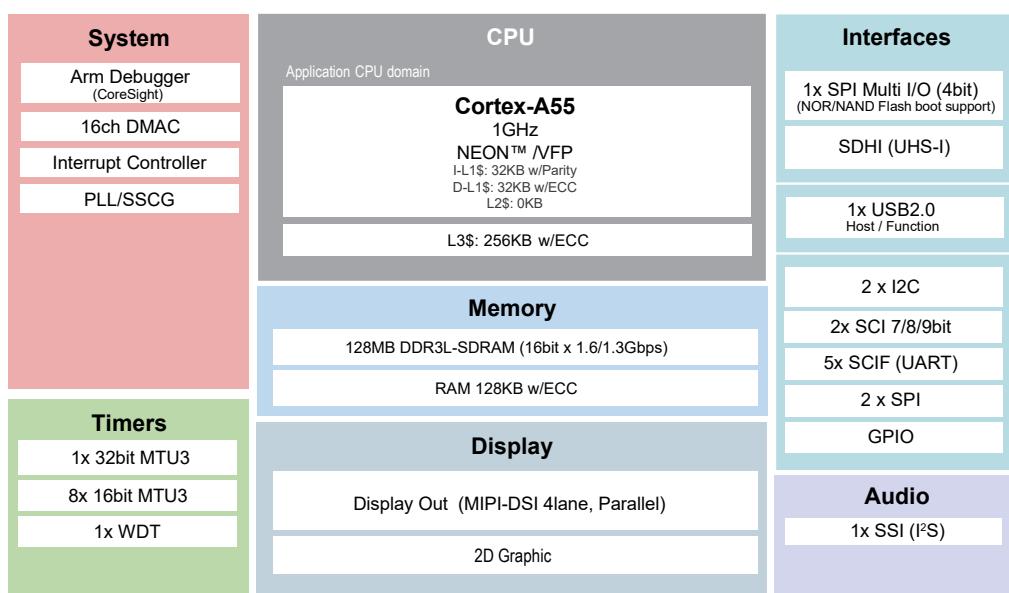
### Features

- 64bit 1GHz Arm Cortex-A55 with NEON
- Built-in 128MB DDR3L SDRAM
- LCD controller up to WXGA (1280x800) with parallel RGB and MIPI-DSI (4lane) interface
- 2D Drawing engine
- QSPI NOR/NAND Flash boot
- Enable 2-layer PCB design
- SDHI for high-speed Wi-Fi® module
- I²S for audio interface
- USB 2.0 Interface for USB camera
- UART/SPI/I²C for sensors

### Applications

- Consumer products
- Smart home and building automation
- Healthcare
- Industrial applications
- Office automation

### Block Diagram

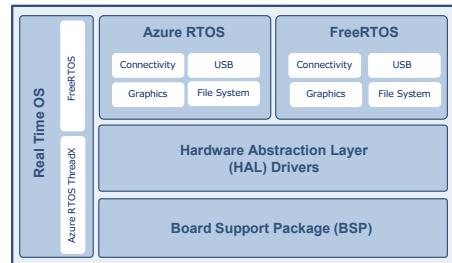


\* Due to pin multi-functionality, not all functions can be simultaneously used.

## Software Package

The Renesas RZ/A Flexible Software Package (FSP) is designed to provide easy-to-use, scalable, high-quality software for embedded system designs using RZ MPUs.

The FSP is based on an open software ecosystem of production-ready drivers, supporting FreeRTOS, Azure RTOS or bare-metal programming. It also includes a selection of other middleware stacks, providing great flexibility for migrating code from older systems or developing new applications from scratch.



Flexible Software Package (FSP)

## Tools and Support

The e<sup>2</sup> studio IDE provides support with intuitive configurators and intelligent code generation to make programming and debugging easier and faster.

	Renesas
<b>Development Environments</b>	e <sup>2</sup> studio
<b>Compilers</b>	GNU Arm Embedded Toolchain
<b>ICEs</b>	J-Link series from Segger
<b>Supported RTOS</b>	FreeRTOS, Azure RTOS

## Evaluation Kits

- Evaluate key features of RZ/A3M MPU and develop high-resolution HMI and other embedded systems applications
- Includes MIPI graphics expansion board (5inch TFT display, 720\*1280 pixel)
- Features on-board debugging using SEGGER-J-Link
- Order the kit and download documentation, design package, development tools, and software at [www.renesas.com/ek-rza3m](http://www.renesas.com/ek-rza3m)
- Orderable part number: **RTK9EKZA3MS10001BE**



## Ordering Information

	<b>R9A07G066M04GBG</b>
<b>CPU/Frequency</b>	Cortex-A55/1.0GHz
<b>RAM</b>	128MB DDR3L 128KB SRAM
<b>Supported Flash</b>	Quad SPI NOR/NAND Flash
<b>LCD interface</b>	Parallel/ MIPI 4-lane
<b>Connectivity</b>	1xUSB2.0(Host/Device) 1xSDHI
<b>T<sub>j</sub></b>	-40 to 110°C
<b>Package</b>	BGA 244pin 17mm x 17mm 0.8mm pitch

For more information, visit  
[www.renesas.com/RZA3M](http://www.renesas.com/RZA3M)

